Heat Resistance Comparison (Reference Value)
Cepla SA101 Other Polyimide

- Extend work life in applications in high temperature environments
- Improve the specifications of equipment mounted on ovens, etc.

Heat resistance	Cepla SA101	Other
Thermal deformation temperature (18.56kg/cm^2)	470℃	360℃
Continuous operating temperature (Actual value)	300℃～350℃	250℃
Linear expansion coefficient（ppm/℃）	35(25~450℃)	54(23~300℃)

Comparison of mechanical strength (reference value)
Cepla SA101 Other Polyimide

- High mechanical strength
- Weight reduction during wear resistance

Mechanical strength	Cepla SA101	Other
Tensile strength(260℃)	47	37
Bending strength(260℃)	51	45
Bend modulus(260℃)	3.6	1.4
Rockwell Hardness	115	45~58

Characteristic comparison (reference value) Cepla SA101 Other Polyimide

Semiconductor manufacturing equipment applications Plasma etching equipment, annealing equipment parts

Plasma immunity, low outgassing, low water absorption

	Cepla SA101	Other Pi
O2Plasma immunity (etching speed) μg/cm2·h	6.6	9.2
Gas emission characteristics in vacuum（Torr·l/sec/cm2）	$5.5x10^{-4}$ （Measuring temperature200℃）	$2.0x10^{-3}$ （Measuring temperature200℃）
Water absorption%（23℃x 24h）	0.03	0.24